

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL
 MINIMUM ANNULAR RING 0.05mm (2ML) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

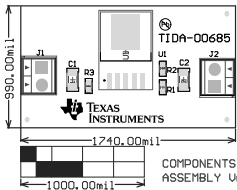
SURFACE FINISH: IMMERSION GOLD (ENG) ENEPIG
 MM. TN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAIL METAL SILK

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00685	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Assembly Top	TID #: TIDA-00685		
PLOT NAME = Top Layer Assembly Drawing	GENERATED : 10/20/2015 11:58:56 AM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Enter name of project	Haod Cao
SCALE: 0.62	ALTIM DESIGNER VERSION: 14.3.14.34663

PROJECT TITLE: Fast Response, Small Size Power Solution Reference Design for GPRS Module

DESIGNED FOR: Public Release

FILE NAME: TID_PcbDoc

Layer	Name	Material	Thickness	Constant	Board Layer Stack
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BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENG) ENERPIC
 MM. TN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAIL METAL SILK



PROJECT TITLE:
Fast Response, Small Size Power Solution Reference Design for GPRS Module

DESIGNED FOR:
Public Release

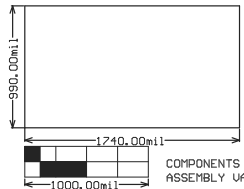
FILE NAME:
TID_PcbDoc

ENGINEER:
Enter name of project

LAYOUT BY:
Hao Cao

SCALE: 0.62

ALTIM DESIGNER VERSION:
14.3.14.34663



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE

BOARD #: TIDA-00685 REV: E1 SUN REV: Not In Version Control

LAYER NAME = Assembly Top TID #: TIDA-00685

PLOT NAME = Bottom Layer Assembly Drawing GENERATED : 10/20/2015 11:59:01 AM TEXAS INSTRUMENTS

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